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### DESCRIPTION

The SX8724C is a data acquisition system based on Semtech's low power ZoomingADC™ technology. It directly connects most types of miniature sensors with a general purpose microcontroller.

With 3 differential inputs, it can adapt to multiple sensor systems. Its digital outputs are used to bias or reset the sensing elements.

### APPLICATIONS

- Industrial pressure sensing
- Industrial temperature sensing
- Industrial chemical sensing
- Barometer
- Compass

### FEATURES

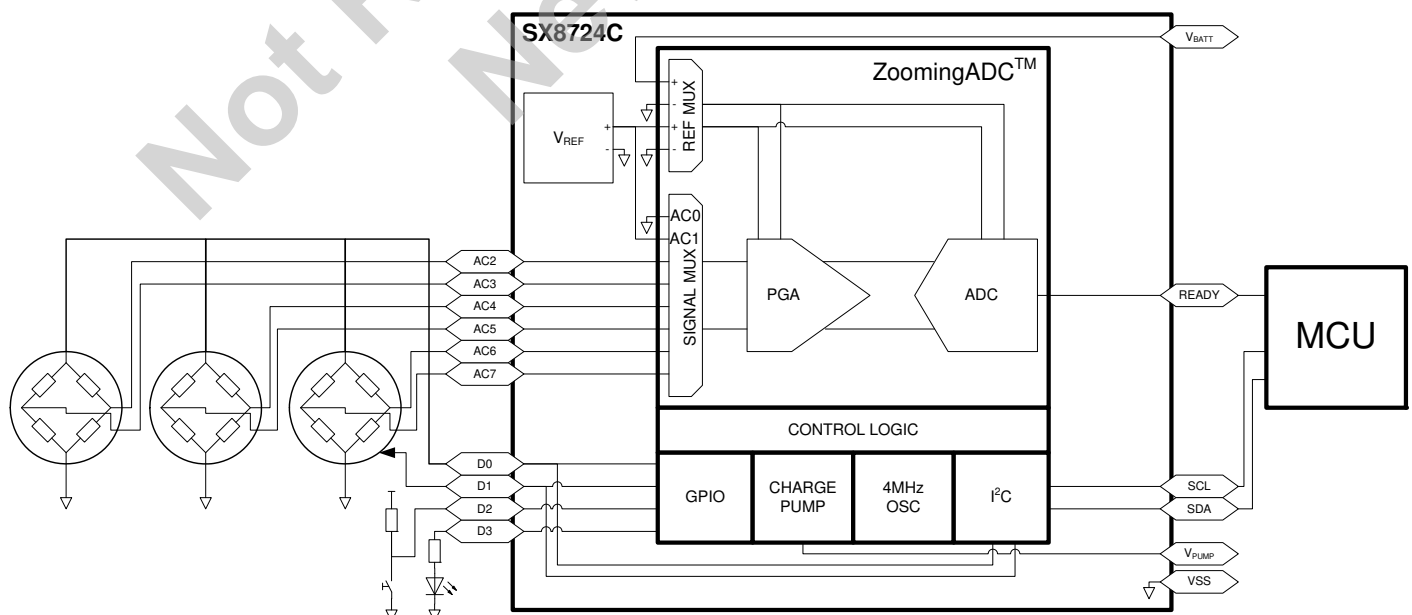
- Up to 16-bit differential data acquisition
- Programmable gain: (1/12 to 1000)
- Sensor offset compensation up to 15 times full scale of input signal
- 3 differential or 6 single-ended signal inputs
- Programmable Resolution versus Speed versus Supply current
- Digital outputs to bias Sensors
- Internal or external voltage reference
- Internal time base
- Low-power (250 uA for 16b @ 250 S/s)
- Fast I2C interface with external address option, no clock stretching required

### ORDERING INFORMATION

DEVICE	PACKAGE	REEL QUANTITY
SX8724CWLTDT	MLPQ-W-16 4x4	1000

- Available in tape and reel only
- WEEE/RoHS compliant, Pb-Free and Halogen Free.

### FUNCTIONAL BLOC DIAGRAM



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## ELECTRICAL SPECIFICATIONS

### 1 Absolute Maximum Ratings

**Note** The Absolute Maximum Ratings, in table below, are stress ratings only. Functional operation of the device at conditions other than those indicated in the Operating Conditions sections of this specification is not implied. Exposure to the absolute maximum ratings, where different to the operating conditions, for an extended period may reduce the reliability or useful lifetime of the product.

**Table 1. Absolute Maximum Ratings**

Parameter	Symbol	Condition	Min	Max	Units
Power supply	VBATT		V <sub>SS</sub> - 0.3	6.5	V
Storage temperature	TSTORE		-55	150	°C
Temperature under bias	TBIAS		-40	140	°C
Input voltage	VINABS	All inputs	V <sub>SS</sub> - 300	VBATT + 300	mV
Peak reflow temperature	TPKG			260	°C
ESD conditions	ESDHBM	Human Body Model ESD	2000		V
Latchup			100		mA

## 2 Operating Conditions

Unless otherwise specified:  $V_{REF,ADC} = V_{BATT}$ ,  $V_{IN} = 0V$ , Over-sampling frequency  $f_s = 250$  kHz, PGA3 on with Gain = 1, PGA1&PGA2 off, offsets  $GDOFF2 = GDOFF3 = 0$ . Power operation: normal ( $I_{bAmpAdc}[1:0] = I_{bAmpPga}[1:0] = '01'$ ).

For resolution  $n = 12$  bits:  $OSR = 32$  and  $NELCONV = 4$ .

For resolution  $n = 16$  bits:  $OSR = 256$  and  $NELCONV = 2$ .

Bandgap chopped at  $NELCONV$  rate. If  $V_{BATT} < 4.2V$ , Charge Pump is forced on. If  $V_{BATT} > 4.2V$ , Charge Pump is forced off.

**Table 2. Operating conditions limits**

Parameter	Symbol	Comment/Condition	Min	Typ	Max	Unit
Power supply	$V_{BATT}$		2.4		5.5	V
Operating temperature	TOP		-40		125	°C

**Table 3. Electrical Characteristics**

Parameter	Symbol	Comment/Condition	Min	Typ	Max	Unit
<b>CURRENT CONSUMPTION<sup>1</sup></b>						
Active current, 5.5V	IOP55	16 b @ 250 Sample/s ADC, $f_s = 125$ kHz		250	350	$\mu A$
		16 b @ 1kSample/s PGA3 + ADC, $f_s = 500$ kHz		700	900	
		16 b + gain 1000 @ 1kSample/s PGA3,2,1 + ADC, $f_s = 500$ kHz		1000	1350	
Active current, 3.3V	IOP33	16 b @ 250 Sample/s ADC, $f_s = 125$ kHz		150		$\mu A$
		16 b @ 1 kSample/s PGA3 + ADC, $f_s = 500$ kHz		300		
		16 b + gain 1000 @ 1kSample/s PGA3,2,1 + ADC, $f_s = 500$ kHz		850		
Sleep current	ISLEEP	@25°C		75		nA
		up to 85°C		100		
		@125°C		150	200	
<b>TIME BASE</b>						
Max ADC Over-Sampling frequency	$f_{smax}$	@25°C	425	500	575	kHz
ADC Over-Sampling frequency drift	$f_{ST}$			0.15		% / °C
<b>DIGITAL I/O</b>						
Input logic high	$V_{IH}$		0.7			$V_{BATT}$
Input logic low	$V_{IL}$				0.3	$V_{BATT}$
Output logic high	$V_{OH}$	$I_{OH} < 4$ mA			$V_{BATT}-0.4$	V
Output logic low	$V_{OL}$	$I_{OL} < 4$ mA	0.4			V
<b>SCL and SDA I/O</b>						
Input logic high	$V_{IH}$		0.7			$V_{BATT}$

**Table 3. Electrical Characteristics**

Parameter	Symbol	Comment/Condition	Min	Typ	Max	Unit
Input logic low	VIL				0.25	VBATT
<b>Leakages currents</b>						
Input leakage current	I <sub>LeakIn</sub>	Digital input mode, no pull-up or pull-down	-100		100	nA
<b>VREF: Internal Bandgap Reference</b>						
Absolute output voltage	VBG	VBATT > 3V	1.19	1.22	1.25	V
Variation over Temperature	VBT	VBATT > 3V, over Temperature	-1.5		+1.5	%
Total Output Noise	VBN	VBATT > 3V			1	mVrms

- The device can be operated in either active or sleep states. The Sleep state is complete shutdown, but the active state can have a variety of different current consumptions depending on the settings. Some examples are given here: The Sleep state is the default state after power-on-reset. The chip can then be placed into an active state after a valid I2C communication is received.

**Table 4. ZoomingADC Specifications**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>ANALOG INPUT CHARACTERISTICS</b>						
Differential Input Voltage Range V <sub>IN</sub> = V <sub>INP</sub> -V <sub>INN</sub>		Gain=1, OSR=32, VREF=5V. <b>Note 1</b>	-2.42		+2.42	V
		Gain=100, OSR=32, VREF=5V	-24.2		+24.2	mV
		Gain=1000, OSR=32, VREF=5V	-2.42		+2.42	mV
<b>PROGRAMMABLE GAIN AMPLIFIER</b>						
Total PGA Gain	GD <sub>TOT</sub>	<b>Note 1</b>	1/12		1000	V/V
PGA1 Gain	GD <sub>1</sub>	(see <b>Table 11, page 22</b> )	1		10	V/V
PGA2 Gain	GD <sub>2</sub>	(see <b>Table 12, page 23</b> )	1		10	V/V
PGA3 Gain	GD <sub>3</sub>	Step = 1/12 V/V (see <b>Table 13, page 23</b> )	1/12		127/12	V/V
Gain Settings Precision (each stage)		Gain ≥ 1	-3	±0.5	+3	%
Gain Temperature Dependence				±5		ppm / °C
PGA2 Offset	GD <sub>OFF2</sub>	Step = 0.2 V/V (see <b>Table 12, page 23</b> )	-1		+1	V/V
PGA3 Offset	GD <sub>OFF3</sub>	Step = 1/12 V/V (see <b>Table 13, page 23</b> )	-63/12		+63/12	V/V
Offset Settings Precision (PGA2 or PGA3)		<b>Note 2</b>	-3	±0.5	+3	%
Offset Temperature Dependence				±5		ppm / °C
Input Impedance on PGA1 (see <b>section 11.1, page 47</b> )		Gain = 1. <b>Note 3</b>	1200	1350		kΩ
		Gain = 10. <b>Note 3</b>	250	300		kΩ
Input Impedance on PGA2,3		Gain = 1. <b>Note 3</b>	150	200		kΩ
Output RMS Noise per over-sample		PGA1. <b>Note 4</b>		205		μV
		PGA2. <b>Note 4</b>		340		μV
		PGA3. <b>Note 4</b>		365		μV

**Table 4. ZoomingADC Specifications**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>ADC STATIC PERFORMANCES</b>						
Resolution (No Missing Codes)	n	<b>Note 5</b> <b>Note 6</b>	6		16	Bits
Gain Error		<b>Note 7</b>		±0.15		%
Offset Error		n = 16 bits. <b>Note 8</b>		±1		LSB
Integral Non-Linearity	INL	resolution n = 12 bits. <b>Note 9</b>		±0.6		LSB
		resolution n = 16 bits. <b>Note 9</b>		±1.5		LSB
Differential Non-Linearity	DNL	resolution n = 12 bits. <b>Note 10</b>		±0.5		LSB
		resolution n = 16 bits. <b>Note 10</b>		±0.5		LSB
Power Supply Rejection Ratio DC	PSRR	V <sub>BATT</sub> = 5V +/- 0.3V. <b>Note 11</b>		78		dB
		V <sub>BATT</sub> = 3V +/- 0.3V. <b>Note 11</b>		72		dB
<b>ADC DYNAMIC PERFORMANCES</b>						
Conversion Time	T <sub>CONV</sub>	n = 12 bits. <b>Note 12</b>		133		fs cycles
		n = 16 bits. <b>Note 12</b>		517		fs cycles
Throughput Rate (Continuous Mode)	1/T <sub>CONV</sub>	n = 12 bits, f <sub>s</sub> = 250 kHz		1.88		kSps
		n = 16 bits, f <sub>s</sub> = 250 kHz		0.483		kSps
PGA Stabilization Delay		<b>Note 13</b> (see <b>Table 12, page 23</b> )		OSR		fs cycles
<b>ZADC ANALOG QUIESCENT CURRENT</b>						
ADC Only Consumption	I <sub>Q</sub>	V <sub>BATT</sub> = 5.5V/3.3V		285/210		μA
PGA1 Consumption		V <sub>BATT</sub> = 5.5V/3.3V		104/80		μA
PGA2 Consumption		V <sub>BATT</sub> = 5.5V/3.3V		67/59		μA
PGA3 Consumption		V <sub>BATT</sub> = 5.5V/3.3V		98/91		μA
<b>ANALOG POWER DISSIPATION : All PGAs &amp; ADC Active</b>						
Normal Power Mode		V <sub>BATT</sub> = 5.5V/3.3V. <b>Note 14</b>		4.0/2.0		mW
3/4 Power Reduction Mode		V <sub>BATT</sub> = 5.5V/3.3V. <b>Note 15</b>		3.2/1.6		mW
1/2 Power Reduction Mode		V <sub>BATT</sub> = 5.5V/3.3V. <b>Note 16</b>		2.4/1.1		mW
1/4 Power Reduction Mode		V <sub>BATT</sub> = 5.5V/3.3V. <b>Note 17</b>		1.5/0.7		mW

- (1) Gain defined as overall PGA gain  $G_{TOT} = G_{D1} \times G_{D2} \times G_{D3}$ . Maximum input voltage is given by:  $V_{IN,MAX} = \pm(V_{REF} / 2) (OSR / OSR + 1)$ .
- (2) Offset due to tolerance on  $G_{Doff2}$  or  $G_{Doff3}$  setting. For small intrinsic offset, use only ADC and PGA1.
- (3) Measured with block connected to inputs through  $A_{mux}$  block. Normalized input sampling frequency for input impedance is  $f_s = 500$  kHz ( $f_s$  max, worst case). This figure must be multiplied by 2 for  $f_s = 250$  kHz, 4 for  $f_s = 125$  kHz. Input impedance is proportional to  $1/f_s$ .
- (4) Figure independent from gain and sampling frequency.  $f_s$ . The effective output noise is reduced by the over-sampling ratio
- (5) Resolution is given by  $n = 2 \log_2(OSR) + \log_2(NELCONV)$ .  $OSR$  can be set between 8 and 1024, in powers of 2.  $NELCONV$  can be set to 1, 2, 4 or 8.
- (6) If a ramp signal is applied to the input, all digital codes appear in the resulting ADC output data.
- (7) Gain error is defined as the amount of deviation between the ideal (theoretical) transfer function and the measured transfer function (with the offset error removed).
- (8) Offset error is defined as the output code error for a zero volt input (ideally, output code = 0). For 1 LSB offset,  $NELCONV$  must be at least 2.
- (9) INL defined as the deviation of the DC transfer curve of each individual code from the best-fit straight line. This specification holds over the full scale.
- (10) DNL is defined as the difference (in LSB) between the ideal (1 LSB) and measured code transitions for successive codes.
- (11) Values for Gain = 1. PSRR is defined as the amount of change in the ADC output value as the power supply voltage changes.



- (12) Conversion time is given by:  $T_{CONV} = (N_{ELCONV}(OSR + 1) + 1) / f_s$ . *OSR* can be set between 8 and 1024, in powers of 2. *NELCONV* can be set to 1, 2, 4 or 8.
- (13) PGAs are reset after each writing operation to registers **RegACCfg1-5**, corresponding to change of configuration or input switching. The ADC should be started only some delay after a change of PGA configuration through these registers. Delay between change of configuration of PGA or input channel switching and ADC start should be equivalent to *OSR* (between 8 and 1024) number of cycles. This is done by writing bit *Start* several cycles after *PGA* settings modification or channel switching. This delay does not apply to conversions made without the *PGAs*.
- (14) Nominal (maximum) bias currents in *PGAs* and *ADC*, i.e.  $I_{bAmpPga}[1:0] = '11'$  and  $I_{bAmpAdc}[1:0] = '11'$ .
- (15) Bias currents in *PGAs* and *ADC* set to 3/4 of nominal values, i.e.  $I_{bAmpPga}[1:0] = '10'$ ,  $I_{bAmpAdc}[1:0] = '10'$ .
- (16) Bias currents in *PGAs* and *ADC* set to 1/2 of nominal values, i.e.  $I_{bAmpPga}[1:0] = '01'$ ,  $I_{bAmpAdc}[1:0] = '01'$ .
- (17) Bias currents in *PGAs* and *ADC* set to 1/4 of nominal values, i.e.  $I_{bAmpPga}[1:0] = '00'$ ,  $I_{bAmpAdc}[1:0] = '00'$ .

Not Recommended for  
New Designs

## 2.1 Timing Characteristics

**Table 5. General timings**

Parameter	Symbol	Comment/Condition	Min	Typ	Max	Unit
<b>ADC INTERRUPT (READY) TIMING SPECIFICATIONS</b>						
READY pulse width	t <sub>IRQ</sub>	<b>Note 1</b>		1		1/fs
<b>STARTUP TIMES</b>						
Startup sequence time at POR	t <sub>START</sub>				800	μs
Time to enable RC from Sleep after an I2C command	t <sub>RCEN</sub>				450	μs

(1) The READY pulse indicates End of Conversion. This is a Positive pulse of duration equal to one cycle of the ADC sampling rate in “continuous mode”.

See also [Figure 17, page 33](#).

### 2.1.1 POR Waveforms

At device power-on or after a software reset

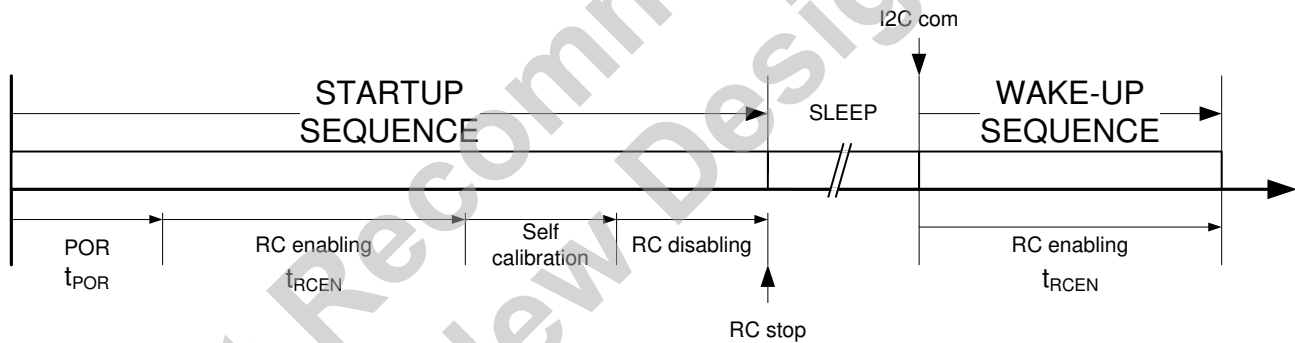


Figure 1. Power-On-Reset waveform

**2.1.2 I2C interface timings**
**Table 6. Digital interface**

Parameter	Symbol	STANDARD-MODE			FAST-MODE			Unit
		Min	Typ	Max	Min	Typ	Max	
<b>I2C TIMING SPECIFICATIONS Note 1</b>								
SCL clock frequency	fSCL	0		100	0		400	kHz
SCL timeout ( optional mode ) Note 2	tSCLTO	35			35			ms
SCL Low Pulsewidth	tL	4.7			1.3			μs
SCL High Pulsewidth	tH	4.0			0.6			μs
Start Condition Hold Time	tSCH	0.6			0.6			μs
Data Setup Time	tDS	250			100 Note 3			ns
Data Hold Time	tDH	0 Note 4		3.45	0		0.9	μs
Setup Time for Repeated Start	trSU	4.7			0.6			μs
Stop Condition Setup Time	tPSU	4.0			0.6			μs
Bus Free Time between a STOP Condition and a START Condition	tBF	4.7			1.3			μs
Pulsewidth of Spike Suppressed	tSUP		100			100		ns
Capacitive load for each bus line	CB			400			400	pF
Noise margin at the LOW level for each connected device (including hysteresis)	V <sub>nL</sub>	0.1VBATT			0.1VBATT			V
Noise margin at the HIGH level for each connected device (including hysteresis)	V <sub>nH</sub>	0.2VBATT			0.2VBATT			V

- (1) All timings specifications are referred to VILmin and VIHmax voltage levels defined for the SCL and SDA pins.
- (2) The digital interface is reset if the SCL is low more than tSCLTO duration. This is the default mode at startup. The timeout can be disabled by register setting.
- (3) A Fast-mode I2C-bus device can be used in a Standard-mode I2C-bus system.
- (4) The device internally provides a hold time of at least 300 ns for the SDA signal (referred to the VIHmin of the SCL signal) to bridge the undefined region of the falling edge of SCL.
- (5) Cb = total capacitance of one bus line in pF. If mixed with Hs-mode devices, faster fall-times according to Table 6 are allowed.

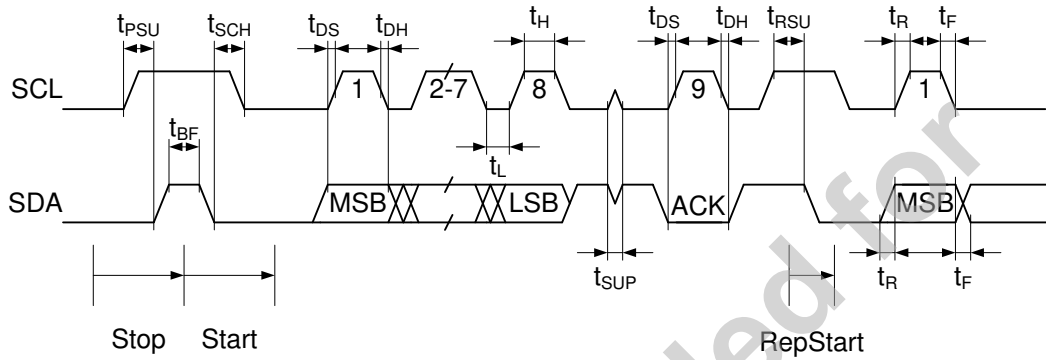
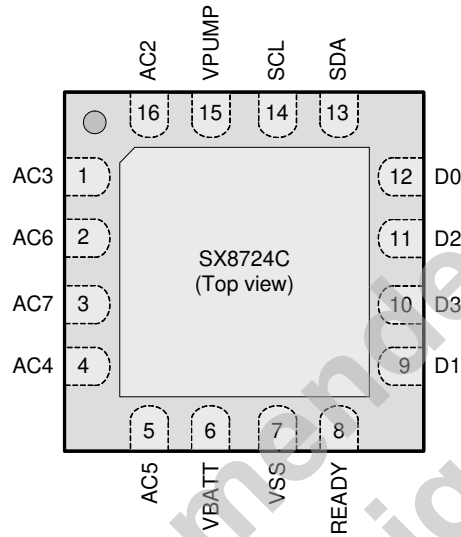
**2.1.3 I2C timing Waveforms**


Figure 2. Definition of timing for F/S-mode on the I2C-bus.

## CIRCUIT DESCRIPTION

### 3 Pin Configuration



### 4 Marking Information



nnnnn = Part Number  
 yyww = Date Code<sup>1</sup>  
 xxxxx = Semtech Lot Number  
 xxxxx

1.Date codes and Lot numbers starting with the 'E' character are used for Engineering samples

## 5 Pin Description

**Note** The bottom pin is internally connected to VSS. It should also be connected to VSS on PCB to reduce noise and improve thermal behavior.

Pin	Name	Type	Function
1	AC3	Analog Input	Differential sensor input in conjunction with AC2
2	AC6	Analog Input	Differential sensor input in conjunction with AC7
3	AC7	Analog Input	Differential sensor input in conjunction with AC6
4	AC4	Analog Input	Differential sensor input in conjunction with AC5
5	AC5	Analog Input	Differential sensor input in conjunction with AC4
6	VBATT	Power Input	2.4V to 5.5V power supply
7	VSS	Power Input	Chip ground
8	READY	Digital Output	Conversion complete flag.
9	D1	Digital IO + analog input	Digital output sensor drive (VBATT or VSS)
			VREF input in optional operating mode
			I2C address bit 1. Msb address bits are fuse programmed.
10	D3	Digital IO	Digital output sensor drive (VBATT or VSS)
11	D2	Digital IO	Digital output sensor drive (VBATT or VSS)
12	D0	Digital IO + analog output	Digital output sensor drive (VBATT or VSS)
			VREF output in optional operating mode
			I2C address bit 0. MSB address bits are fuse programmed.
13	SDA	Digital IO	I2C data line
14	SCL	Digital IO	I2C clock line. Up to 400 kHz.
15	VPUMP	Power IO	Charge pump output. Raises analog switch supply above VBATT if VBATT supply is too low. Recommended range for capacitor is 1nF to 10 nF. Connect the capacitor to ground.
16	AC2	Analog Input	Differential sensor input in conjunction with AC3

## 6 General Description

The SX8724C is a complete low-power acquisition path with programmable gain, acquisition speed and resolution.

### 6.1 Bloc diagram

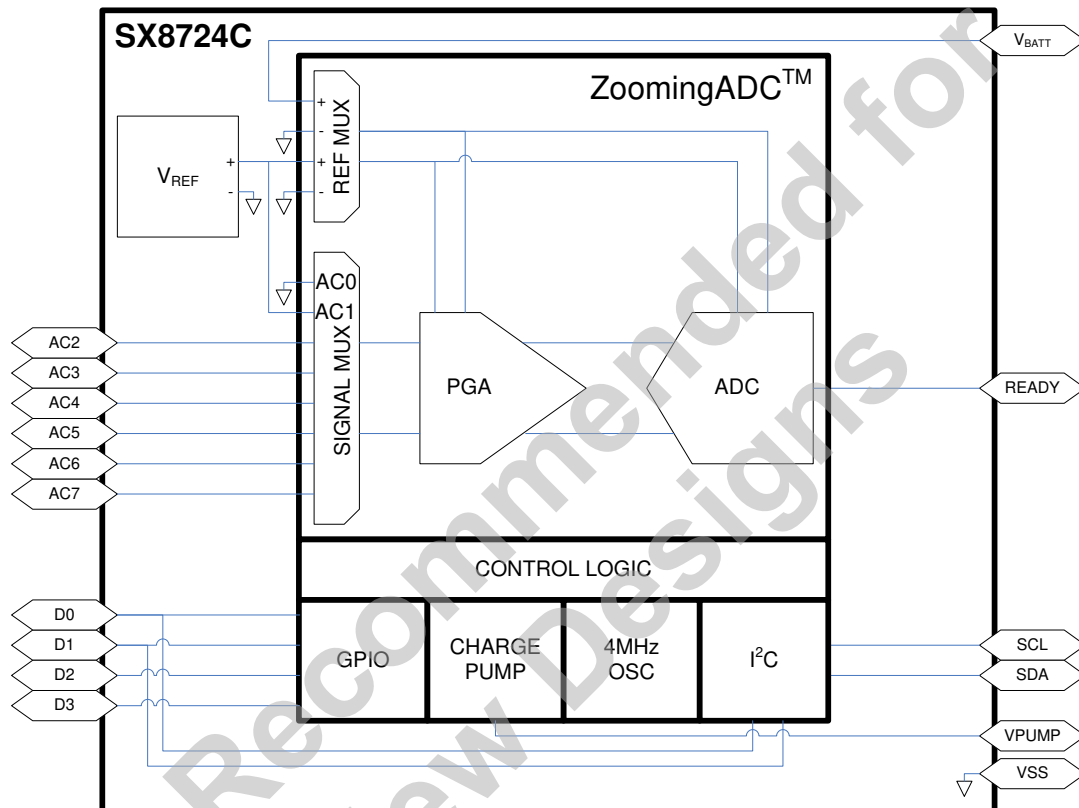


Figure 3. SX8724C bloc diagram

### 6.2 VREF

The internally generated  $V_{REF}$  is a trimmed bandgap reference with a nominal value of 1.22V that provides a stable voltage reference for the ZoomingADC.

This reference voltage is directly connected to one of the ZoomingADC reference multiplexer inputs.

The bandgap voltage stability is only guaranteed for  $V_{BATT}$  voltages of 3V and above. As  $V_{BATT}$  drops down to 2.4V, the bandgap voltage could reduce by up to 50mV.

The bandgap has relatively weak output drive so it is recommended that if the bandgap is required as a signal input then  $PGA1$  must be enabled with gain = 1.

### 6.3 GPIO

The  $GPIO$  block is a multipurpose 4 bit input/output port. In addition to digital behavior,  $D0$  and  $D1$  pins can be programmed as analog pins in order to be used as output (reference voltage monitoring) and input for an external

reference voltage (For further details see [Figure 6](#), [Figure 7](#), [Figure 8](#) and [Figure 9](#)). Each port terminal can be individually selected as digital input or output.

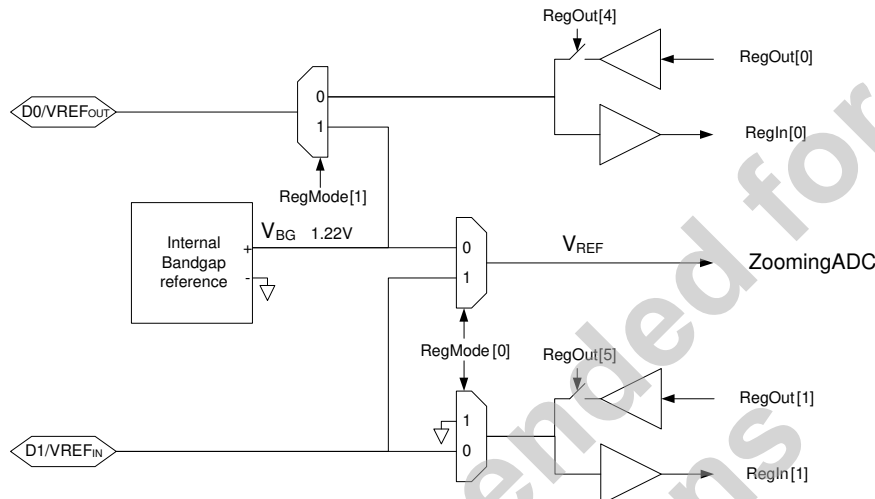


Figure 4. GPIO bloc diagram

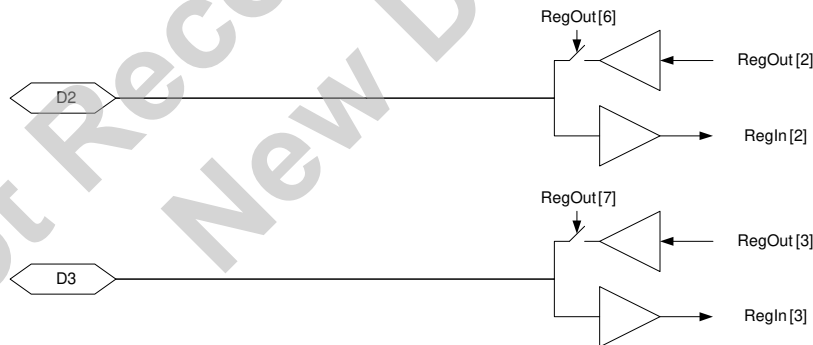


Figure 5. Digital IO bloc diagram

The direction of each bit within the *GPIO* block (input only or input/output) can be individually set using the bits of the **RegOut** (address 0x40) register. If  $D[x]Dir = 1$ , both the input and output buffer are active on the corresponding *GPIO* block pin. If  $D[x]Dir = 0$ , the corresponding *GPIO* block pin is an input only and the output buffer is in high impedance. After power on reset the *GPIO* block pins are in input/output mode ( $D[x]Dir$  are reset to 1).

The input values of *GPIO* block are available in **RegIn** (address 0x41) register (read only). Reading is always direct - there is no debounce function in the *GPIO* block. In case of possible noise on input signals, an external hardware filter has to be realized. The input buffer is also active when the *GPIO* block is defined as output and the effective value on the pin can be read back.



Data stored in the LSB bits of **RegOut** register are outputted at *GPIO* block if  $D[x]Dir=1$ . The default values after power on reset is low (0).

The digital pins are able to deliver a driving current up to 8 mA.

When the bits *VrefD0Out* and *VrefD1In* in the **RegMode** (address 0x70) register are set to 1 the *D0* and *D1* pins digital behavior are automatically bypassed in order to either input or output the voltage reference signals.

### 6.3.1 Optional Operating Mode: External Vref

*D0* and *D1* are multi-functional pins with the following functions in different operating modes (see **RegMode** register for control settings):

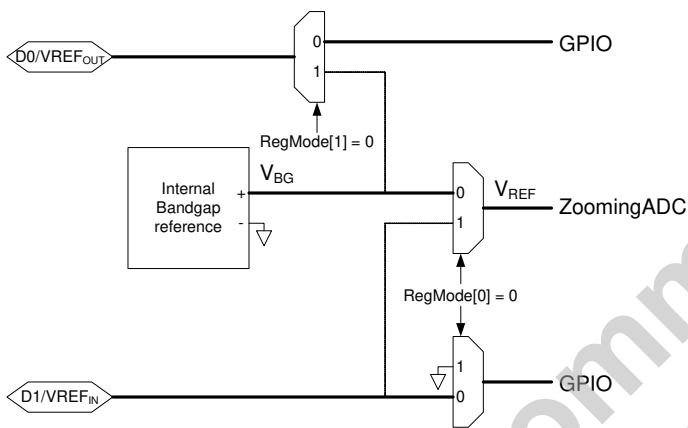


Figure 6. *D0* and *D1* are Digital Inputs / Outputs

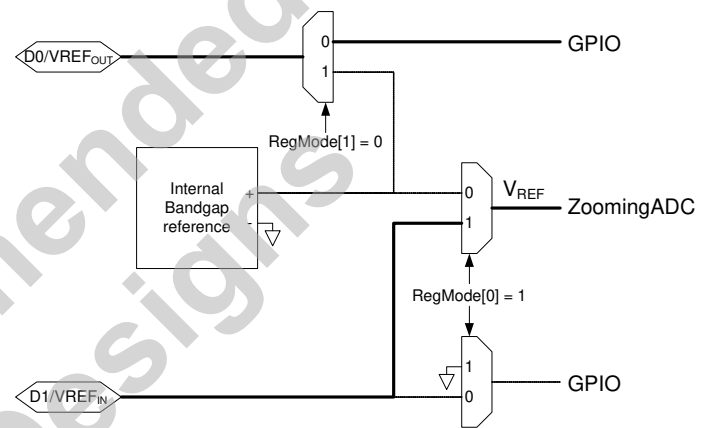


Figure 7. *D1* is Reference Voltage Input and *D0* is Digital Input / Output

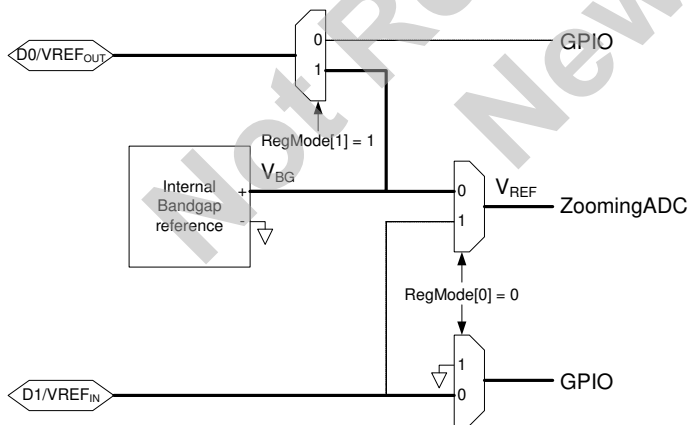


Figure 8. *D1* is Digital Input / Output and *D0* Reference Voltage Output

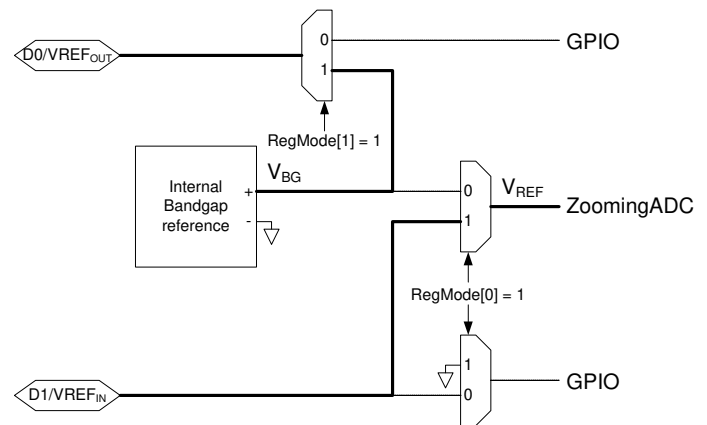


Figure 9. *D0* is Reference Voltage Output and *D1* is Reference Voltage Input

This allows external monitoring of the internal bandgap reference or the ability to use an external reference input for the ADC, or the option to filter the internal  $V_{REF}$  output before feeding back as  $V_{REF,ADC}$  input. The internally generated  $V_{REF}$  is a trimmed as ADC reference with a nominal value of 1.22V. When using an external  $V_{REF,ADC}$  input, it may have any value between 0V and  $V_{BATT}$ . Simply substitute the external value for 1.22 V in the ADC conversion calculations.

## 6.4 Charge Pump

This block generates a supply voltage able to power the analog switch drive levels on the chip higher than  $V_{BATT}$  if necessary.

If  $V_{BATT}$  voltage drops below 4.2V then the block should be activated. If  $V_{BATT}$  voltage is greater than 4.2V then  $V_{BATT}$  may be switched straight through to the  $VPUMP$  output. If the charge pump is not activated then  $VPUMP = V_{BATT}$ .

If control input bit  $MultForceOff = 1$  in **RegMode** (address 0x70) register then the charge pump is disabled and  $V_{BATT}$  is permanently connected to  $VPUMP$  output.

If control input bit  $MultForceOn = 1$  in **RegMode** register then the charge pump is permanently enabled. This overrides  $MultForceOff$  bit in **RegMode** register.

An external capacitor is required on  $VPUMP$  pin. This capacitor should be large enough to ensure that generated voltage is smooth enough to avoid affecting conversion accuracy but not so large that it gives an unacceptable settling time. A recommended value is around 2.2nF.

## 6.5 RC Oscillator

This block provides the master clock reference for the chip. It produces a clock at 4 MHz which is divided internally in order to generate the clock sources needed by the other blocks.

The oscillator technique is a low power relaxation design and it is designed to vary as little as possible over temperature and supply voltage.

This oscillator is trimmed at manufacture chip test.

The  $RC$  oscillator will start up after a chip reset to allow the trimming values to be read and calibration registers and I2C address set to their default fused values. Once this has been done, the oscillator will be shut down and the chip will enter a sleep state while waiting for an I2C communication.

The worst case duration from reset ( or POR ) to the sleep state is 800us.

### 6.5.1 Wake-up from sleep

When the device is in sleep state, the  $RC$  oscillator will start up after a communication. The start up sequence for the  $RC$  oscillator is 450us in worst case.

During this time, the internal blocs using the  $RC$  can not be used: no ADC conversion can be started.

## 7 ZoomingADC

### 7.1 Overview

The *ZoomingADC* is a complete and versatile low-power analog front-end interface typically intended for sensing applications. In the following text the *ZoomingADC* will be referred as *ZADC*.

The key features of the *ZADC* are:

- Programmable 6 to 16-bit dynamic range over-sampled ADC
- Flexible gain programming between 1/12 and 1000
- Flexible and large range offset compensation
- Differential or single-ended input
- 2-channel differential reference inputs
- Power saving modes

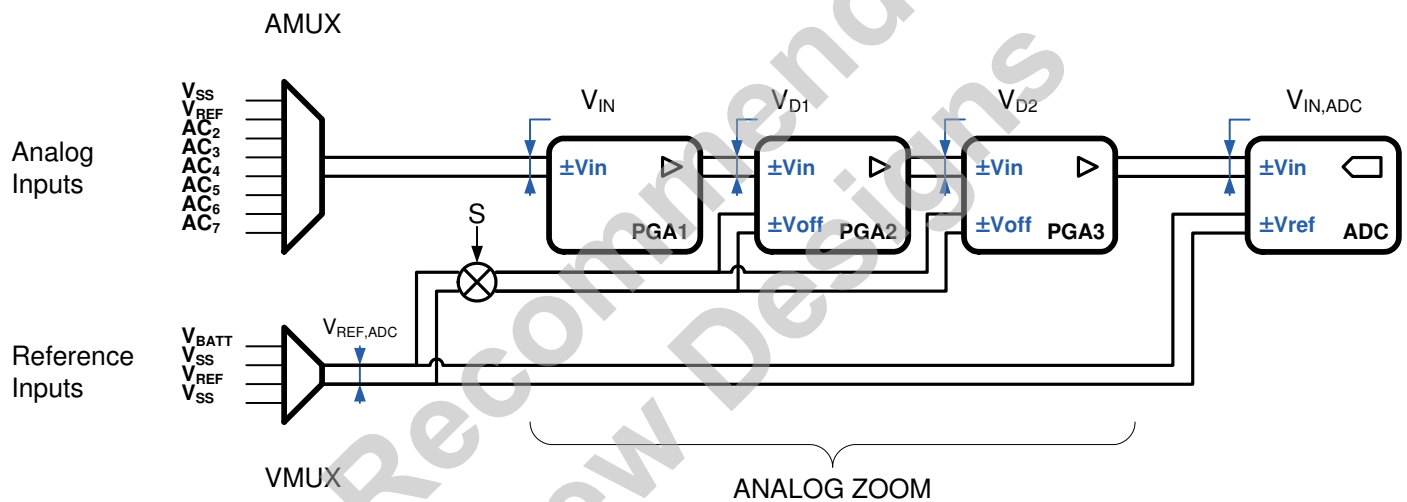


Figure 10. ZADC General Functional Block Diagram

The total acquisition chain consists of an input multiplexer, 3 programmable gain amplifier stages and an over sampled A/D converter. The reference voltage can be selected on two different channels. Two offset compensation amplifiers allow for a wide offset compensation range. The programmable gain and offset allow the application to zoom in on a small portion of the reference voltage defined input range.

#### 7.1.1 Acquisition Chain

**Figure 10, page 18** shows the general block diagram of the acquisition chain (AC). A control block (not shown in **Figure 10**) manages all communications with the I2C peripheral. The clocking is derived from the internal 4 MHz Oscillator.

Analog inputs can be selected through an 8 input multiplexer, while reference input is selected between two differential channels. It should however be noted that only 7 acquisition channels (including the VREF) are available when configured as single ended since the input amplifier is always operating in differential mode with both positive and negative input selected through the multiplexer.

The core of the zooming section is made of three differential programmable amplifiers (*PGA*). After selection of an input and reference signals  $V_{IN}$  and  $V_{REF,ADC}$  combination, the input voltage is modulated and amplified through stages 1 to 3. Fine gain programming up to 1'000 V/V is possible. In addition, the last two stages provide programmable offset. Each amplifier can be bypassed if needed.

The output of the cascade of *PGA* is directly fed to the analog-to-digital converter (*ADC*), which converts the signal  $V_{IN,ADC}$  into digital.

Like most *ADCs* intended for instrumentation or sensing applications, the ZoomingADC™ is an over-sampled converter<sup>1</sup>. The *ADC* is a so-called incremental converter; with bipolar operation (the *ADC* accepts both positive and negative differential input voltages). In first approximation, the *ADC* output result relative to full-scale (*FS*) delivers the quantity:

$$\frac{OUT_{ADC}}{FS/2} \cong \frac{V_{IN,ADC}}{V_{REF}/2}$$

**Equation 1**

in two's complement (see [Equation 18](#) and [Equation 19](#), page 33 for details). The output code  $OUT_{ADC}$  is  $-FS/2$  to  $+FS/2$  for  $V_{IN,ADC} = -V_{REF,ADC}/2$  to  $+V_{REF,ADC}/2$  respectively. As will be shown,  $V_{IN,ADC}$  is related to input voltage  $V_{IN}$  by the relationship:

$$V_{IN,ADC} = GD_{TOT} \cdot V_{IN} - GD_{Off,TOT} \cdot S \cdot V_{REF} \quad [V]$$

**Equation 2**

where  $GD_{TOT}$  is the total *PGA* gain,  $GD_{Off,TOT}$  is the total magnitude of *PGA* offset and  $S$  is the sign of the offset (see [Table 9](#), page 21).

### 7.1.2 Programmable Gain Amplifiers

As seen in [Figure 10](#), page 18, the zooming function is implemented with three programmable gain amplifiers (*PGA*). These are:

- *PGA1*: coarse gain tuning
- *PGA2*: medium gain and offset tuning
- *PGA3*: fine gain and offset tuning. Should be set ON for high linearity data acquisition

All gain and offset settings are realized with ratios of capacitors. The user has control over each *PGA* activation and gain, as well as the offset of stages 2 and 3. These functions are examined hereafter.

1. Over-sampled converters are operated with a sampling frequency  $f_s$  much higher than the input signal's Nyquist rate (typically  $f_s$  is 20-1'000 times the input signal bandwidth). The sampling frequency to throughput ratio is large (typically 10-500). These converters include digital decimation filtering. They are mainly used for high resolution, and/or low-to-medium speed applications.

### 7.1.3 PGA & ADC Enabling

Depending on the application objectives, the user may enable or bypass each *PGA* stage. This is done according to the word *Enable* and the coding given in **Table 7**. To reduce power dissipation, the *ADC* can also be inactivated while idle.

**Table 7. ADC and PGA Enabling**

Enable (RegACCfg1[3:0])	Block
XXX0 XXX1	ADC disabled ADC enabled
XX0X XX1X	PGA1 disabled PGA1 enabled
X0XX X1XX	PGA2 disabled PGA2 enabled
0XXX 1XXX	PGA3 disabled PGA3 enabled

### 7.2 ZoomingADC Registers

The system has a bank of eight 8-bit registers: six registers are used to configure the acquisition chain (**RegAcCfg0** to **RegAcCfg5**), and two registers are used to store the output code of the analog-to-digital conversion (**RegAcOutMsb** & **Lsb**).

**Table 8. Peripheral Registers to Configure the Acquisition Chain (AC) and to Store the Analog-to-Digital Conversion (ADC) Result**

Register Name	Bit position							
	7	6	5	4	3	2	1	0
RegACOutLsb	Out[7:0] <b>Note 1</b>							
RegACOutMsb	Out[15:8]							
RegACCfg0 Default values:	Start 0, <b>Note 2</b>	SetNelconv 01, <b>Note 3</b>		SetOsr 010, <b>Note 4</b>			Continuous 0, <b>Note 5</b>	- 0, <b>Note 6</b>
RegACCfg1 Default value:	IbAmpAdc 11, <b>Note 7</b>		IbAmpPga 11, <b>Note 8</b>		Enable 0000, <b>Note 9</b>			
RegACCfg2 Default value:	SetFs 00, <b>Note 10</b>		Pga2Gain 00, <b>Note 12</b>		Pga2Offset 0000, <b>Note 14</b>			
RegACCfg3 Default value:	Pga1Gain 0, <b>Note 11</b>	Pga3Gain 0001100, <b>Note 13</b>						
RegACCfg4 Default value:	- 0	Pga3Offset 0000000, <b>Note 15</b>						
RegACCfg5 Default value:	Busy 0, <b>Note 16</b>	Def 0, <b>Note 17</b>	Amux 00000, <b>Note 18</b>				Vmux 0, <b>Note 19</b>	

(r = read; w = write; rw = read & write)

- (1) **Out:** (r) digital output code of the analog-to-digital converter. (*MSB* = *Out[15]*)
- (2) **Start:** (w) setting this bit triggers a single conversion (after the current one is finished). This bit always reads back 0.

- (3) **SetNelconv:** (rw) sets the number of elementary conversions to  $2^{(SetNelconv[1:0])}$ . To compensate for offsets, the input signal is chopped between elementary conversions (1,2,4,8).
- (4) **SetOsr:** (rw) sets the over-sampling rate (*OSR*) of an elementary conversion to  $2^{(3+SetOsr[2:0])}$ . *OSR* = 8, 16, 32, ..., 512, 1024.
- (5) **Continuous:** (rw) setting this bit starts a conversion. When this bit is 1, A new conversion will automatically begin directly when the previous one is finished.
- (6) Reserved
- (7) **IbAmpAdc:** (rw) sets the bias current in the ADC to  $0.25 \times (1 + IbAmpAdc[1:0])$  of the normal operation current (25, 50, 75 or 100% of nominal current). To be used for low-power, low-speed operation.
- (8) **IbAmpPga:** (rw) sets the bias current in the PGAs to  $0.25 \times (1 + IbAmpPga[1:0])$  of the normal operation current (25, 50, 75 or 100% of nominal current). To be used for low-power, low-speed operation.
- (9) **Enable:** (rw) enables the ADC modulator (bit 0) and the different stages of the PGAs (*PGAi* by bit  $i=1,2,3$ ). PGA stages that are disabled are bypassed.
- (10) **SetFs:** (rw) These bits set the over sampling frequency of the acquisition chain. Expressed as a fraction of the oscillator frequency, the sampling frequency is given as: 11 ' 500 kHz, 10 ' 250 kHz, 01 ' 125 kHz, 00 ' 62.5 kHz.
- (11) **Pga1Gain:** (rw) sets the gain of the first stage: 0 ' 1, 1 ' 10.
- (12) **Pga2Gain:** (rw) sets the gain of the second stage: 00 ' 1, 01 ' 2, 10 ' 5, 11 ' 10.
- (13) **Pga3Gain:** (rw) sets the gain of the third stage to *Pga3Gain*[6:0] 1/12.
- (14) **Pga2Offset:** (rw) sets the offset of the second stage between -1 and +1, with increments of 0.2. The *MSB* gives the sign (0 positive, 1 negative); amplitude is coded with the bits *Pga2Offset*[5:0].
- (15) **Pga3Offset:** (rw) sets the offset of the third stage between -5.25 and +5.25, with increments of 1/12. The *MSB* gives the sign (0 positive, 1 negative); amplitude is coded with the bits *Pga3Offset*[5:0].
- (16) **Busy:** (r) set to 1 if a conversion is running.
- (17) **Def:** (w) sets all values to their defaults (*PGA* disabled, max speed, nominal modulator bias current, 2 elementary conversions, over-sampling rate of 32) and starts a new conversion without waiting the end of the preceding one.
- (18) **Amux**(4:0): (rw) *Amux*[4] sets the mode (0 ' differential inputs, 1 ' single ended inputs with *A0*= common reference) *Amux*[3] sets the sign (0 ' straight, 1 ' cross) *Amux*[2:0] sets the channel.
- (19) **Vmux:** (rw) sets the differential reference channel (0 ' *VBATT*, 1 ' *VREF*).

### 7.3 Input Multiplexers (AMUX and VMUX)

The ZoomingADC has analog inputs *AC0* to *AC7* and reference inputs. Let us first define the differential input voltage *VIN* and reference voltage *VREF,ADC* respectively as:

$$V_{IN} = V_{INP} - V_{INN} \quad [V]$$

Equation 3

$$V_{REF} = V_{REFP} - V_{REFN} \quad [V]$$

Equation 4

As shown in **Table 9**, the inputs can be configured in two ways: either as 4 differential channels ( $V_{INi} = AC1 - AC0, \dots, V_{IN4} = AC7 - AC6$ ), or *AC0* can be used as a common reference, providing 7 signal paths all referred to *AC0*. The control word for the analog input selection is *Amux*. Notice that the *Amux* bit 4 controls the sign of the input voltage.

**Table 9. Analog Input Selection**

Amux (RegACCfg5[5:1])	VINP	VINN	Amux (RegACCfg5[5:1])	VINP	VINN
<b>Sign S = 1</b>			<b>Sign S = -1</b>		
00x00	AC1(VREF)	AC0(Vss)	01x00	AC1(Vss)	AC0(VREF)

**Table 9. Analog Input Selection**

Amux (RegACCFg5[5:1])	VINP	VINN	Amux (RegACCFg5[5:1])	VINP	VINN
<b>Sign S = 1</b>			<b>Sign S = -1</b>		
00x01	AC3	AC2	01x01	AC2	AC3
00x10	AC5	AC4	01x10	AC4	AC5
00x11	AC7	AC6	01x11	AC6	AC7
10000	AC0(Vss)	AC0(Vss)	11000	AC0(Vss)	AC0(Vss)
10001	AC1(VREF)		11001		AC1(VREF)
10010	AC2		11010		AC2
10011	AC3		11011		AC3
10100	AC4		11100		AC4
10101	AC5		11101		AC5
10110	AC6		11110		AC6
10111	AC7		11111		AC7

Similarly, the reference voltage is chosen among two differential channels ( $V_{REF} = V_{BATT} - V_{SS}$ ,  $V_{REF} = V_{BG} - V_{SS}$  or  $V_{REF} = V_{REF,IN} - V_{SS}$ ) as shown in [Table 10](#). The selection bit is  $V_{mux}$ . The reference inputs  $V_{REFP}$  and  $V_{REFN}$  (common-mode) can be up to the power supply range.

**Table 10. Analog reference Input Selection**

Vmux (RegACCFg5[0])	VREFP	VREFN
0	$V_{REF} = V_{BATT}$	Vss
1	$V_{REF} = V_{BG}$ or $V_{REF,IN}^1$	Vss

- External voltage reference on D1 GPIO pin. See [section 6.3 on page 14](#) about GPIO and "RegMode[0x70]" on page 46.

## 7.4 First Stage Programmable Gain Amplifier (PGA1)

The first stage can have a buffer function (unity gain) or provide a gain of 10 (see [Table 11](#)). The voltage  $V_{D1}$  at the output of  $PGA1$  is:

$$V_{D1} = GD_1 \cdot V_{IN} \quad [V]$$

**Equation 5**

where  $GD_1$  is the gain of  $PGA1$  (in V/V) controlled with the  $Pga1Gain$  bit.

**Table 11. PGA1 gain settings**

Pga1Gain bit (RegACCFg3[7])	PGA1 gain [V/V] $GD_1$ [V/V]
0	1
1	10

### 7.5 Second Stage Programmable Gain Amplifier (PGA2)

The second *PGA* has a finer gain and offset tuning capability, as shown in [Table 12](#). The  $V_{D2}$  voltage at the output of *PGA2* is given by:

$$V_{D2} = GD_2 \cdot V_{D1} - GD_{off2} \cdot S \cdot V_{REF} \quad [V]$$

**Equation 6**

where  $GD_2$  and  $GD_{OFF2}$  are respectively the gain and offset of *PGA2* (in V/V). These are controlled with the words *Pga2Gain[1:0]* and *Pga2Offset[3:0]*.

**Table 12. PGA2 gain and offset settings**

Pga2Gain bitfield (RegACCFg2[5:4])	PGA2 gain [V/V] $GD_2$ [V/V]	Pga2Offset bitfield (RegACCFg2[3:0])	PGA2 offset $GD_{OFF2}$ [V/V]
00	1	0000	0
01	2	0001	+0.2
10	5	0010	+0.4
11	10	0011	+0.6
		0100	+0.8
		0101	+1
		1000	0
		1001	-0.2
		1010	-0.4
		1011	-0.6
		1100	-0.8
		1101	-1.0

### 7.6 Third Stage Programmable Gain Amplifier (PGA3)

The finest gain and offset tuning is performed with the third and last *PGA* stage, according to the coding of [Table 13](#).

**Table 13. PGA3 Gain and Offset Settings**

Pga3Gain bitfield (RegACCFg3[6:0])	PGA3 Gain $GD_3$ [V/V]	Pga3Offset bitfield (RegACCFg4[6:0])	PGA3 Offset $GD_{OFF3}$ [V/V]
0000000	0	0000000	0
0000001	1/12 (=0.083)	0000001	+1/12 (=0.083)
...	...	...	...
0000110	6/12	0010000	+16/12
...	...	...	...
0001100	12/12	0100000	32/12
0010000	16/12	...	...
...	...	0111111	+63/12 (=+5.25)
0100000	32/12	1000000	0



**Table 13. PGA3 Gain and Offset Settings**

Pga3Gain bitfield (RegACCfg3[6:0])	PGA3 Gain $GD_3$ [V/V]	Pga3Offset bitfield (RegACCfg4[6:0])	PGA3 Offset $GDOff_3$ [V/V]
...	...	1000001	-1/12 (= -0.083)
1000000	64/12	1000010	-2/12
...	...	...	...
1111111	127/12 (=10.58)	1010000	-16/12
		...	...
		1100000	-32/12
		...	...
		1111111	-63/12 (= -5.25)

The output of  $PGA_3$  is also the input of the ADC. Thus, similarly to  $PGA_2$ , we find that the voltage entering the ADC is given by:

$$V_{IN,ADC} = GD_3 \cdot V_{D2} - GDOff_3 \cdot S \cdot V_{REF} \quad [V]$$

**Equation 7**

where  $GD_3$  and  $GDOff_3$  are respectively the gain and offset of  $PGA_3$  (in V/V). The control words are  $Pga3Gain[6:0]$  and  $Pga3Offset[6:0]$ .

To remain within the signal compliance of the  $PGA$  stages (no saturation), the condition:

$$|V_{IN}|, |V_{D1}|, |V_{D2}| < \frac{V_{BATT}}{2}$$

**Equation 8**

must be verified.

To remain within the signal compliance of the ADC (no saturation), the condition:

$$|V_{IN,ADC}| < \left( \frac{V_{REF}}{2} \right) \left( \frac{OSR - 1}{OSR} \right)$$

**Equation 9**

must be verified.

Finally, combining **Equation 5** to **Equation 7** for the three *PGA* stages, the input voltage  $V_{IN,ADC}$  of the *ADC* is related to  $V_{IN}$  by:

$$V_{IN,ADC} = GD_{TOT} \cdot V_{IN} - GDoff_{TOT} \cdot S \cdot V_{REF} \quad [V]$$

**Equation 10**

where the total *PGA* gain is defined as:

$$GD_{TOT} = GD_3 \cdot GD_2 \cdot GD_1$$

**Equation 11**

and the total *PGA* offset is:

$$GDoff_{TOT} = GDoff_3 + GD_3 \cdot GDoff_2$$

**Equation 12**

### 7.6.1 *PGA* Ranges

**Figure 11** and **Figure 12** illustrates the limits for the maximal conversion precision according to the common mode voltage ( $V_{COMMON}$ ), the *ADC* over-sampling frequency ( $f_s$ ) and *PGA* gains. The best linearity performances can be